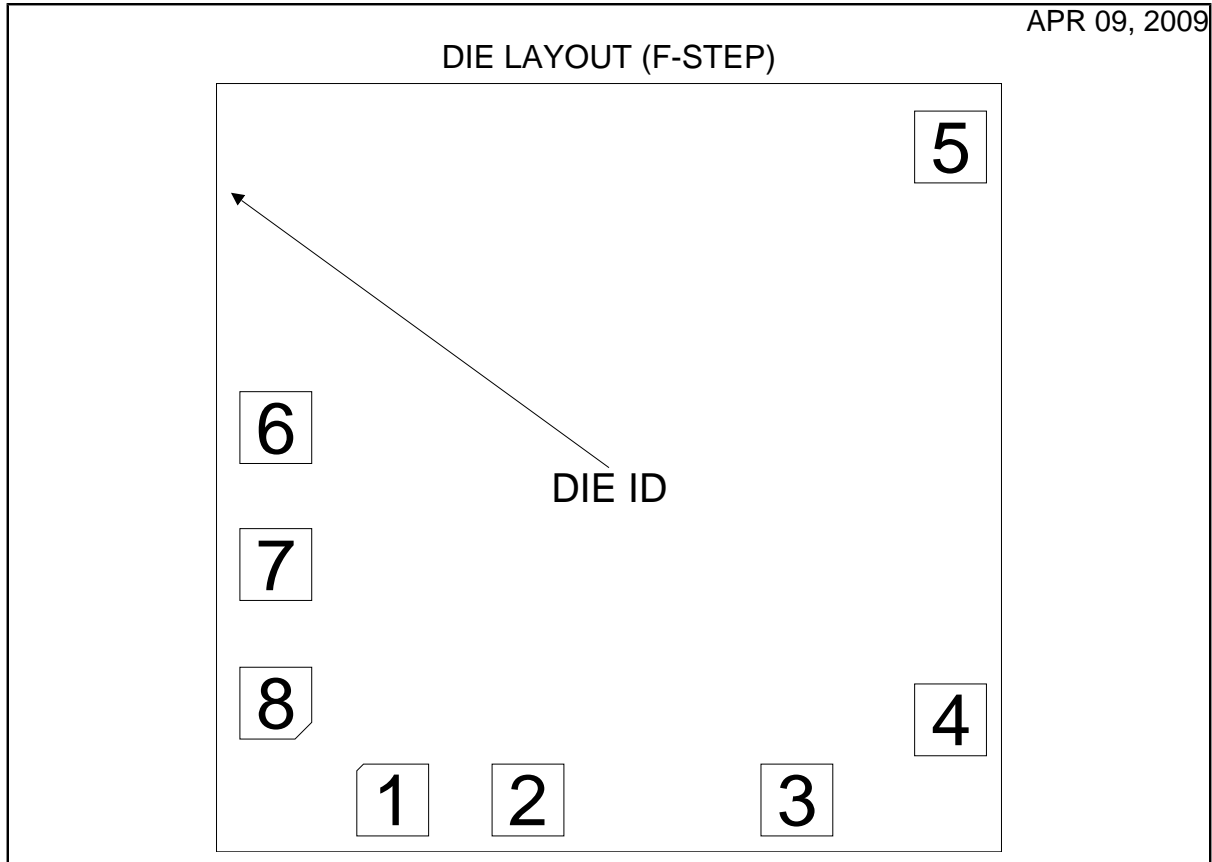


LM101 MDR MCD3000A
OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM101F	Bond Pad Opening Size (min)	109.22 μ m x 109.22 μ m
Die Step	F	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1193.80 μ m x 1168.40 μ m 47.0mils x 46.0mils	Back Side Connection	Floating
Thickness	304.8 μ m Nominal		
Min Pitch	205.74 μ m		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(F-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
BALANCE COMP	1	-329	-505	109	x	109
INPUT -	2	-123	-505	109	x	109
INPUT +	3	286	-505	109	x	109
V -	4	519	-384	109	x	109
BALANCE	5	519	488	109	x	109
OUTPUT	6	-507	61	109	x	109
V+	7	-507	-147	109	x	109
COMPENSATION	8	-507	-358	109	x	109

LM101 MDR MCD3000A
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Notes

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